

## 2SK2839

Chopper Regulator, DC-DC Converter and Motor Drive Applications

- 4 V gatedrive
- Low drain-source ON resistance :  $R_{DS(ON)} = 30 \text{ m}\Omega$  (typ.)
- High forward transfer admittance :  $|Y_{fs}| = 11 \text{ S}$  (typ.)
- Low leakage current :  $I_{DSS} = 100 \text{ }\mu\text{A}$  (max) ( $V_{DS} = 30 \text{ V}$ )
- Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

### Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	30	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	30	V
Gate-source voltage		$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1)	$I_D$	10	A
	Pulse (Note 1)	$I_{DP}$	40	A
Drain power dissipation (Note 2)		$P_D$	2.5	W
Single pulse avalanche energy (Note 3)		$E_{AS}$	282	mJ
Avalanche current		$I_{AR}$	10	A
Repetitive avalanche energy (Note 4)		$E_{AR}$	0.25	mJ
Channel temperature		$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	$-55 \sim 150$	$^\circ\text{C}$

### Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	50	$^\circ\text{C} / \text{W}$

Note 1: Please use devices on condition that the channel temperature is below  $150^\circ\text{C}$ .

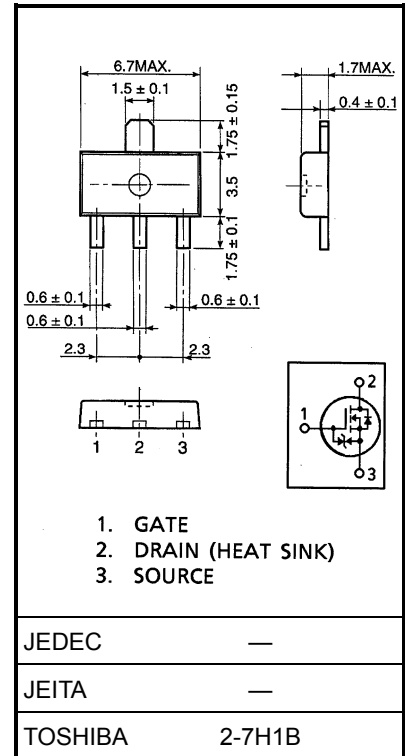
Note 2: Mounted on ceramic substrate ( $25.4 \text{ mm} \times 25.4 \text{ mm} \times 0.8 \text{ mm}$ )

Note 3:  $V_{DD} = 25 \text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 2 \text{ mH}$ ,  $R_G = 25 \text{ }\Omega$ ,  $I_{AR} = 10 \text{ A}$

Note 4: Repetitive rating; Pulse width limited by maximum channel temperature.

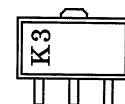
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

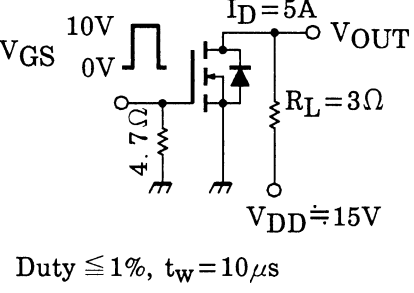


Weight: 0.12 g (typ.)

### Marking



## Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cut-off current		$I_{DSS}$	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	100	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	—	—	V
Gate threshold voltage		$V_{th}$	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	0.8	—	2.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{DS} = 4 \text{ V}, I_D = 5 \text{ A}$	—	45	60	m $\Omega$
			$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$	—	30	40	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$	5	11	—	S
Input capacitance		$C_{iss}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	700	—	pF
Reverse transfer capacitance		$C_{rss}$		—	150	—	
Output capacitance		$C_{oss}$		—	360	—	
Switching time	Rise time	$t_r$	 <p><math>I_D = 5 \text{ A}</math> <math>R_L = 3 \Omega</math> <math>V_{DD} \approx 15 \text{ V}</math> Duty <math>\leq 1\%</math>, <math>t_w = 10 \mu\text{s}</math></p>	—	20	—	ns
	Turn-on time	$t_{on}$		—	25	—	
	Fall time	$t_f$		—	100	—	
	Turn-off time	$t_{off}$		—	300	—	
Total gate charge (gate-source plus gate-drain)		$Q_g$	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	—	26	—	nC
Gate-source charge		$Q_{gs}$		—	20	—	
Gate-drain ("miller") Charge		$Q_{gd}$		—	6	—	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	—	—	—	10	A
Pulse drain reverse current (Note 1)	$I_{DRP}$	—	—	—	40	A
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-2.0	V
Reverse recovery time	$t_{rr}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 50 \text{ A} / \mu\text{s}$	—	120	—	ns
Reverse recovery charge	$Q_{rr}$		—	140	—	nC

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